# Automotive – Extended Temperature PSoC® Programmable System-on-Chip

Features

- AEC qualified

- Powerful Harvard-Architecture processor
  - M8C processor speeds up to 12 MHz
  - Two 8 × 8 multiply, 32-bit accumulate
  - Low power at high speed
  - Operating voltage: 4.75 V to 5.25 V
  - Extended temperature range: –40 °C to +125 °C

- Advanced peripherals (PSoC® blocks)
  - 12 Rail-to-Rail analog PSoC blocks provide:
    - Up to 14-Bit analog-to-digital converters (ADCs)
    - Up to 9-Bit digital-to-analog converters (DACs)
    - Programmable gain amplifiers (PGA)
    - Programmable filters and comparators
  - 16 digital PSoC blocks provide:
    - 8- to 32-bit timers and counters, 8- and 16-bit pulse-width modulators (PWMs)
    - CRC and PRS modules
    - Up to four full-duplex or eight half-duplex UARTs
    - Multiple SPI masters or slaves
    - Connectable to all general purpose I/O (GPIO) pins
  - Complex peripherals by combining blocks

- Precision, programmable clocking
  - Internal ±4% 24 MHz oscillator
  - High accuracy 24 MHz with optional 32.768 kHz crystal and phase locked loop (PLL)
  - Optional external oscillator, up to 24 MHz
  - Internal low speed, low power oscillator for Watchdog and Sleep functionality

- Flexible on-chip memory
  - 32K bytes flash program storage, 100 erase/write cycles
  - 2K bytes SRAM data storage
  - In-system serial programming (ISSP)
  - Partial flash updates
  - Flexible protection modes
  - EEPROM emulation in flash

- Programmable pin configurations
  - 25 mA sink, 10 mA drive on all GPIOs
  - Pull up, pull down, high Z, strong, or open drain drive modes on all GPIO
  - Up to 12 analog inputs on GPIO[1]
  - Four 30 mA analog outputs on GPIO
  - Configurable interrupt on all GPIOs

- Additional system resources
  - I^{2}C™ master, slave, or multi-master operation up to 400 kHz
  - Watchdog and sleep timers
  - User-configurable low voltage detection (LVD)
  - Integrated supervisory circuit
  - On-chip precision voltage reference

- Complete development tools
  - Free development software (PSoC Designer™)
  - Full featured in-circuit emulator (ICE) and programmer
  - Full speed emulation
  - Complex breakpoint structure
  - 128 K bytes trace memory
  - Complex events
  - C Compilers, assembler, and linker

Logic Block Diagram
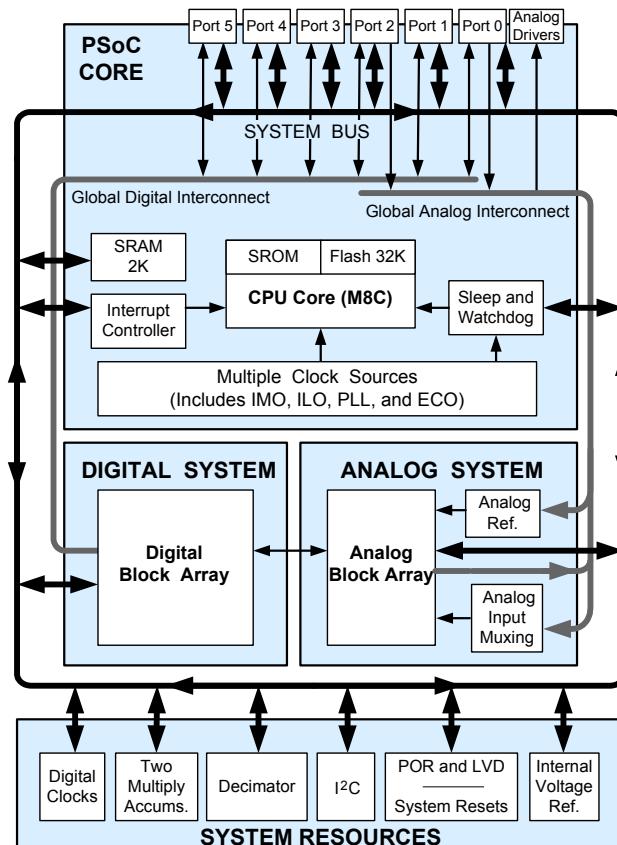
Note
1. There are eight standard analog inputs on the GPIO. The other four analog inputs connect from the GPIO directly to specific switched-capacitor block inputs. See the PSoC Technical Reference Manual for more details

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PSoC Functional Overview

The PSoC programmable system-on-chip family consists of many devices with on-chip controllers. These devices are designed to replace multiple traditional microcontroller unit (MCU)-based system components with one, low cost single-chip programmable device. PSoC devices include configurable blocks of analog and digital logic, as well as programmable interconnects. This architecture enables the user to create customized peripheral configurations that match the requirements of each individual application. Additionally, a fast CPU, Flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts and packages.

The PSoC architecture, as illustrated in the Logic Block Diagram on page 1, is comprised of four main areas: PSoC Core, Digital System, Analog System, and System Resources. Configurable global buses allow all the device resources to be combined into a complete custom system. The PSoC CY8C29x66 family can have up to six I/O ports that connect to the global digital and analog interconnects, providing access to 16 digital blocks and 12 analog blocks.

The PSoC Core is a powerful engine that supports a rich feature set. The core includes a CPU, memory, clocks, and configurable GPIO.

The M8C CPU core is a powerful processor with speeds up to 12 MHz, providing a two MIPS 8-bit Harvard architecture microprocessor. The CPU utilizes an interrupt controller with 25 vectors, to simplify programming of real time embedded events. Program execution is timed and protected using the included Sleep Timer and Watch Dog Timer (WDT).

Memory includes 32K of Flash for program storage and 2K of SRAM for data storage. Program Flash utilizes four protection levels on blocks of 64 bytes, allowing customized software IP protection.

The PSoC device incorporates flexible internal clock generators, including a 24 MHz IMO (internal main oscillator) accurate to ±4% over temperature and voltage. A low power 32 kHz internal low speed oscillator (ILO) is provided for the Sleep Timer and WDT. If crystal accuracy is desired, the ECO (32.768 kHz external crystal oscillator) is available for use as a Real Time Clock (RTC) and can optionally generate a crystal-accurate 24 MHz system clock using a PLL. The clocks, together with programmable clock dividers (as a System Resource), provide the flexibility to integrate almost any timing requirement into the PSoC device.

PSoC GPIOs provide connection to the CPU, digital resources, and analog resources of the device. Each pin's drive mode may be selected from eight options, allowing great flexibility in external interfacing. Every pin also has the capability to generate a system interrupt.

The Digital System

The Digital System is composed of 16 digital PSoC blocks. Each block is an 8-bit resource that can be used alone or combined with other blocks to form 8, 16, 24, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include those listed here.

- PWMs (8- and 16-bit)
- PWMs with Dead Band (8- and 16-bit)
- Counters (8 to 32 bit)
- Timers (8 to 32 bit)
- Full or Half-Duplex 8-bit UART with selectable parity (up to 4 Full-Duplex or 8 Half-Duplex)
- SPI master and slave (up to 8 total)
- I^2C master, slave, or multi-master
- Cyclical Redundancy Checker/Generator (16 bit)
- IrDA (up to 4)
- Pseudo Random Sequence Generators (8 to 32 bit)

The digital blocks can be connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 5.

Figure 1. Digital System Block Diagram
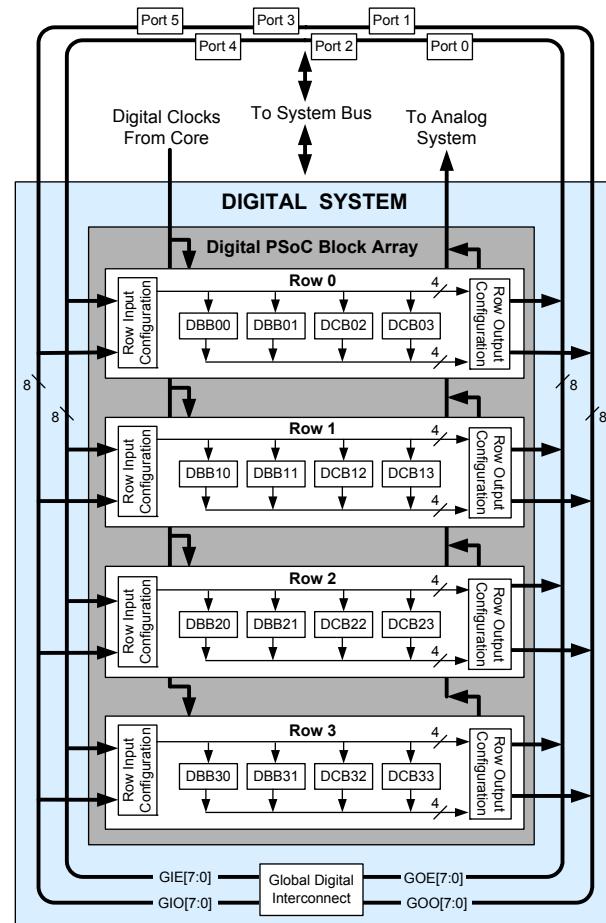
The Analog System

The Analog System is composed of 12 configurable blocks, each comprised of an opamp circuit allowing the creation of complex analog signal flows. Analog peripherals are very flexible and can be customized to support specific application requirements. Some of the common PSoC analog functions for this device (most available as user modules) are as follows:

- ADCs (up to 4, with 6- to 14-bit resolution, selectable as Incremental, Delta-Sigma, and SAR)

- Filters (2, 4, 6, or 8 pole band-pass, low-pass, and notch)

- Amplifiers (up to 4, with selectable gain up to 48x)

- Instrumentation amplifiers (up to 2, with selectable gain up to 93x)

- Comparators (up to 4, with 16 selectable thresholds)

- DACs (up to 4, with 6- to 9-bit resolution)

- Multiplying DACs (up to 4, with 6- to 9-bit resolution)

- High current output drivers (four with 30 mA drive as a PSoC Core resource)

- 1.3 V reference (as a System Resource)

- DTMF Dialer

- Correlators

- Peak Detectors

- Many other topologies possible

Analog blocks are provided in columns of three, which includes one Continuous Time (CT) and two Switched Capacitor (SC) blocks, as shown in Figure 2.

Figure 2. Analog System Block Diagram
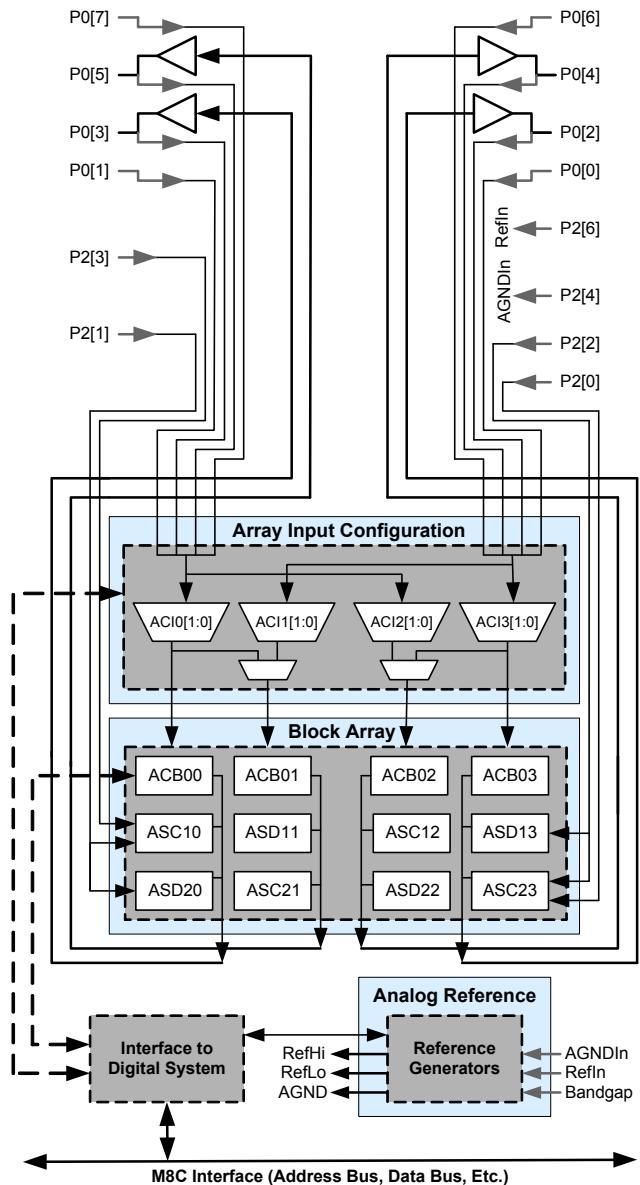
Additional System Resources

System Resources, some of which have been previously listed, provide additional capability useful for complete systems. Additional resources include a multiplier, decimator, low voltage detection, and power on reset. Brief statements describing the merits of each system resource are given below:

■ Digital clock dividers provide three customizable clock frequencies for use in applications. The clocks can be routed to both the digital and analog systems. Additional clocks can be generated using digital PSoC blocks as clock dividers.

■ Two multiply accumulates (MACs) provide fast 8-bit multiplier with 32-bit accumulate to assist in both general math as well as digital filters.

■ The decimator provides a custom hardware filter for digital signal processing applications including the creation of Delta Sigma ADCs.

■ The I²C module provides 0 to 400 kHz communication over two wires. Slave, master, and multi-master modes are all supported.

■ LVD interrupts can signal the application of falling voltage levels, while the advanced POR (Power On Reset) circuit eliminates the need for a system supervisor.

■ An internal 1.3 V voltage reference provides an absolute reference for the analog system, including ADCs and DACs.

PSoC Device Characteristics

Depending on your PSoC device characteristics, the digital and analog systems can have a varying number of digital and analog blocks. The following table lists the resources available for specific PSoC device groups. The PSoC device covered by this data sheet is highlighted in Table 1.

Table 1. PSoC Device Characteristics

PSoC Part Number	Digital I/O	Digital Rows	Digital Blocks	Analog Inputs	Analog Outputs	Analog Columns	Analog Blocks	SRAM Size	Flash Size
CY8C29x66[2]	up to 64	4	16	12	4	4	12	2K	32K
CY8C27x43	up to 44	2	8	12	4	4	12	256 Bytes	16K
CY8C24x94	64	1	4	48	2	2	6	1K	16K
CY8C24x23A[2]	up to 24	1	4	12	2	2	6	256 Bytes	4K
CY8C23x33	up to	1	4	12	2	2	4	256 Bytes	8K
CY8C21x34[2]	up to 28	1	4	28	0	2	4[3]	512 Bytes	8K
CY8C21x23	16	1	4	8	0	2	4[3]	256 Bytes	4K
CY8C20x34	up to 28	0	0	28	0	0	3[3, 4]	512 Bytes	8K

Notes
2. Automotive qualified devices available in this group.
3. Limited analog functionality.
4. Two analog blocks and one CapSense.

Getting Started

For in-depth information, along with detailed programming details, see the *PSoC® Technical Reference Manual*.

For up-to-date ordering, packaging, and electrical specification information, see the latest PSoC device datasheets on the web.

Application Notes

Cypress application notes are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

PSoC Development Kits are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

Free PSoC technical training (on demand, webinars, and workshops), which is available online via www.cypress.com,

covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

Certified PSoC consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC consultant go to the CYPros Consultants web site.

Solutions Library

Visit our growing library of solution focused designs. Here you can find various application designs that include firmware and hardware design files that enable you to complete your designs quickly.

Technical Support

Technical support – including a searchable Knowledge Base articles and technical forums – is also available online. If you cannot find an answer to your question, call our Technical Support hotline at 1-800-541-4736.

Development Tools

PSoC Designer™ is the revolutionary integrated design environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

■ Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration

■ Extensive user module catalog

■ Integrated source-code editor (C and assembly)

■ Free C compiler with no size restrictions or time limits

■ Built-in debugger

■ In-circuit emulation

■ Built-in support for communication interfaces:
  ❑ Hardware and software I^{2}C slaves and masters
  ❑ Full-speed USB 2.0
  ❑ Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are ADCs, DACs, amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this allows you to use more than 100 percent of PSoC's resources for an application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and are linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows you to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an online support Forum to aid the designer.

In-Circuit Emulator

A low-cost, high-functionality in-circuit emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24 MHz) operation.

Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is summarized in four steps:

1. Select User Modules.

2. Configure User Modules.

3. Organize and Connect.

4. Generate, Verify, and Debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called "user modules." User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a PWM User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These user module datasheets explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information you may need to successfully implement your design.

Organize and Connect

You build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. You perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, you perform the "Generate Configuration Files" step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides application programming interfaces (APIs) with high-level functions to control and respond to hardware events at run-time and interrupt service routines that you can adapt as needed.

A complete code development environment allows you to develop and customize your applications in either C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer's debugger (access by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer and allows you to define complex breakpoint events. These include monitoring address and data bus values, memory locations, and external signals.

Pinouts

The automotive CY8C29x66 PSoC device is available in a variety of packages which are listed and illustrated in the following tables. Every port pin (labeled with a "P") is capable of Digital I/O. However, Vss, Vdd, and XRES are not capable of Digital I/O.

28-pin Part Pinout

Table 2. 28-Pin Part Pinout (SSOP)

Pin No.	Type Digital	Type Analog	Pin Name	Description
1	I/O	I	P0[7]	Analog column mux input.
2	I/O	I/O	P0[5]	Analog column mux input and column output.
3	I/O	I/O	P0[3]	Analog column mux input and column output.
4	I/O	I	P0[1]	Analog column mux input.
5	I/O		P2[7]	
6	I/O		P2[5]	
7	I/O	I	P2[3]	Direct switched capacitor block input.
8	I/O	I	P2[1]	Direct switched capacitor block input.
9	Power		Vss	Ground connection.
10	I/O		P1[7]	I^2C Serial Clock (SCL).
11	I/O		P1[5]	I^2C Serial Data (SDA).
12	I/O		P1[3]	
13	I/O		P1[1]	Crystal Input (XTALin), I^2C Serial Clock (SCL), ISSP-SCLK[5].
14	Power		Vss	Ground connection.
15	I/O		P1[0]	Crystal Output (XTALout), I^2C Serial Data (SDA), ISSP-SDATA[5].
16	I/O		P1[2]	
17	I/O		P1[4]	Optional External Clock Input (EXTCLK).
18	I/O		P1[6]	
19	Input		XRES	Active high external reset with internal pull down.
20	I/O	I	P2[0]	Direct switched capacitor block input.
21	I/O	I	P2[2]	Direct switched capacitor block input.
22	I/O		P2[4]	External Analog Ground (AGND).
23	I/O		P2[6]	External Voltage Reference (VRef).
24	I/O	I	P0[0]	Analog column mux input.
25	I/O	I/O	P0[2]	Analog column mux input and column output.
26	I/O	I/O	P0[4]	Analog column mux input and column output.
27	I/O	I	P0[6]	Analog column mux input.
28	Power		Vdd	Supply voltage.

LEGEND: A = Analog, I = Input, and O = Output.

Figure 3. CY8C29466 28-pin PSoC Device

	SSOP	
AI, P0[7] — 1		28 — Vdd
AIO, P0[5] — 2		27 — P0[6], AI
AIO, P0[3] — 3		26 — P0[4], AIO
AI, P0[1] — 4		25 — P0[2], AIO
P2[7] — 5		24 — P0[0], AI
P2[5] — 6		23 — P2[6], External VRef
AI, P2[3] — 7		22 — P2[4], External AGND
AI, P2[1] — 8		21 — P2[2], AI
Vss — 9		20 — P2[0], AI
I2C SCL, P1[7] — 10		19 — XRES
I2C SDA, P1[5] — 11		18 — P1[6]
P1[3] — 12		17 — P1[4], EXTCLK
I2C SCL, XTALin, P1[1] — 13		16 — P1[2]
Vss — 14		15 — P1[0], XTALout, I2C SDA
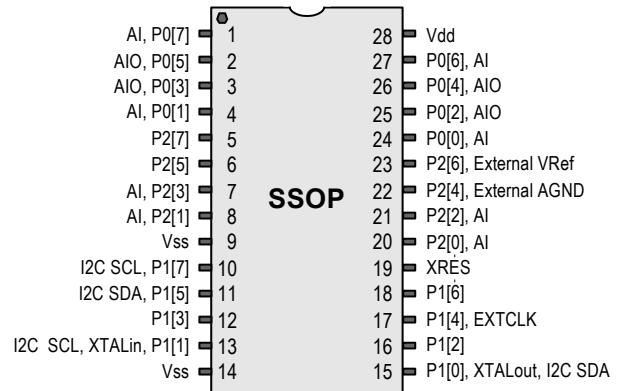
Note

5. These are the ISSP pins, which are not High Z when coming out of POR (Power On Reset). See the *PSoC Technical Reference Manual* for details.

48-pin Part Pinout

Table 3. 48-pin Part Pinout (SSOP)

Pin No.	Type Digital	Type Analog	Pin Name	Description
1	I/O	I	P0[7]	Analog column mux input
2	I/O	I/O	P0[5]	Analog column mux input and column output
3	I/O	I/O	P0[3]	Analog column mux input and column output
4	I/O	I	P0[1]	Analog column mux input
5	I/O		P2[7]	
6	I/O		P2[5]	
7	I/O	I	P2[3]	Direct switched capacitor block input
8	I/O	I	P2[1]	Direct switched capacitor block input
9	I/O		P4[7]	
10	I/O		P4[5]	
11	I/O		P4[3]	
12	I/O		P4[1]	
13	Power		V_{SS}	Ground connection
14	I/O		P3[7]	
15	I/O		P3[5]	
16	I/O		P3[3]	
17	I/O		P3[1]	
18	I/O		P5[3]	
19	I/O		P5[1]	
20	I/O		P1[7]	I²C serial clock (SCL)
21	I/O		P1[5]	I²C serial data (SDA)
22	I/O		P1[3]	
23	I/O		P1[1]	Crystal input (XTALin), I²C serial clock (SCL), ISSP-SCLK[6]
24	Power		V_{SS}	Ground connection
25	I/O		P1[0]	Crystal output (XTALout), I²C Serial Data (SDA), ISSP-SDATA[6]
26	I/O		P1[2]	
27	I/O		P1[4]	Optional external clock (EXTCLK) input
28	I/O		P1[6]	
29	I/O		P5[0]	
30	I/O		P5[2]	
31	I/O		P3[0]	
32	I/O		P3[2]	
33	I/O		P3[4]	
34	I/O		P3[6]	
35	Input		XRES	Active high external reset with internal pull-down
36	I/O		P4[0]	
37	I/O		P4[2]	
38	I/O		P4[4]	
39	I/O		P4[6]	
40	I/O	I	P2[0]	Direct switched capacitor block input
41	I/O	I	P2[2]	Direct switched capacitor block input
42	I/O		P2[4]	External analog ground (AGND)
43	I/O		P2[6]	External voltage reference (V_{REF})
44	I/O	I	P0[0]	Analog column mux input
45	I/O	I/O	P0[2]	Analog column mux input and column output
46	I/O	I/O	P0[4]	Analog column mux input and column output
47	I/O	I	P0[6]	Analog column mux input
48	Power		V_{DD}	Supply voltage

LEGEND: A = Analog, I = Input, and O = Output.

Figure 4. CY8C29666 48-pin PSoC Device

Note
6. These are the ISSP pins, which are not high Z when coming out of POR. See the *PSoC Technical Reference Manual* for details.
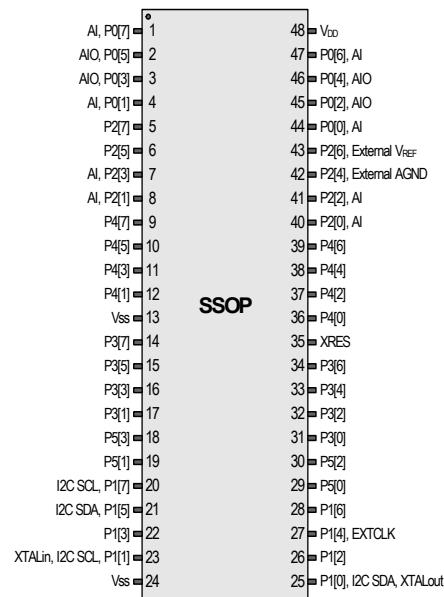
Registers

Register Conventions

This section lists the the registers of the automotive CY8C29x66 PSoC device. For detailed register information, reference the *PSoC Technical Reference Manual.*

The register conventions specific to this section are listed in the following table.

Table 4. Abbreviations

Convention	Description
R	Read register or bit(s)
W	Write register or bit(s)
L	Logical register or bit(s)
C	Clearable register or bit(s)
#	Access is bit specific

Register Mapping Tables

The PSoC device has a total register address space of 512 bytes. The register space is referred to as I/O space and is divided into two banks. The XIO bit in the Flag register (CPU_F) determines which bank the user is currently in. When the XIO bit is set the user is in Bank 1.

Note In the following register mapping tables, blank fields are Reserved and should not be accessed.

Table 5. Register Map Bank 0 Table: User Space

Name	Addr (0, Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access	Name	Addr (0,Hex)	Access
PRT0DR	00	RW	DBB20DR0	40	#	ASC10CR0	80	RW	RDI2RI	C0	RW
PRT0IE	01	RW	DBB20DR1	41	W	ASC10CR1	81	RW	RDI2SYN	C1	RW
PRT0GS	02	RW	DBB20DR2	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PRT0DM2	03	RW	DBB20CR0	43	#	ASC10CR3	83	RW	RDI2LT0	C3	RW
PRT1DR	04	RW	DBB21DR0	44	#	ASD11CR0	84	RW	RDI2LT1	C4	RW
PRT1IE	05	RW	DBB21DR1	45	W	ASD11CR1	85	RW	RDI2RO0	C5	RW
PRT1GS	06	RW	DBB21DR2	46	RW	ASD11CR2	86	RW	RDI2RO1	C6	RW
PRT1DM2	07	RW	DBB21CR0	47	#	ASD11CR3	87	RW		C7	
PRT2DR	08	RW	DCB22DR0	48	#	ASC12CR0	88	RW	RDI3RI	C8	RW
PRT2IE	09	RW	DCB22DR1	49	W	ASC12CR1	89	RW	RDI3SYN	C9	RW
PRT2GS	0A	RW	DCB22DR2	4A	RW	ASC12CR2	8A	RW	RDI3IS	CA	RW
PRT2DM2	0B	RW	DCB22CR0	4B	#	ASC12CR3	8B	RW	RDI3LT0	CB	RW
PRT3DR	0C	RW	DCB23DR0	4C	#	ASD13CR0	8C	RW	RDI3LT1	CC	RW
PRT3IE	0D	RW	DCB23DR1	4D	W	ASD13CR1	8D	RW	RDI3RO0	CD	RW
PRT3GS	0E	RW	DCB23DR2	4E	RW	ASD13CR2	8E	RW	RDI3RO1	CE	RW
PRT3DM2	0F	RW	DCB23CR0	4F	#	ASD13CR3	8F	RW		CF	
PRT4DR	10	RW	DBB30DR0	50	#	ASD20CR0	90	RW	CUR_PP	D0	RW
PRT4IE	11	RW	DBB30DR1	51	W	ASD20CR1	91	RW	STK_PP	D1	RW
PRT4GS	12	RW	DBB30DR2	52	RW	ASD20CR2	92	RW		D2	
PRT4DM2	13	RW	DBB30CR0	53	#	ASD20CR3	93	RW	IDX_PP	D3	RW
PRT5DR	14	RW	DBB31DR0	54	#	ASC21CR0	94	RW	MVR_PP	D4	RW
PRT5IE	15	RW	DBB31DR1	55	W	ASC21CR1	95	RW	MVW_PP	D5	RW
PRT5GS	16	RW	DBB31DR2	56	RW	ASC21CR2	96	RW	I2C_CFG	D6	RW
PRT5DM2	17	RW	DBB31CR0	57	#	ASC21CR3	97	RW	I2C_SCR	D7	#
	18		DCB32DR0	58	#	ASD22CR0	98	RW	I2C_DR	D8	RW
	19		DCB32DR1	59	W	ASD22CR1	99	RW	I2C_MSCR	D9	#
	1A		DCB32DR2	5A	RW	ASD22CR2	9A	RW	INT_CLR0	DA	RW
	1B		DCB32CR0	5B	#	ASD22CR3	9B	RW	INT_CLR1	DB	RW
	1C		DCB33DR0	5C	#	ASC23CR0	9C	RW	INT_CLR2	DC	RW
	1D		DCB33DR1	5D	W	ASC23CR1	9D	RW	INT_CLR3	DD	RW
	1E		DCB33DR2	5E	RW	ASC23CR2	9E	RW	INT_MSK3	DE	RW
	1F		DCB33CR0	5F	#	ASC23CR3	9F	RW	INT_MSK2	DF	RW
DBB00DR0	20	#	AMX_IN	60	RW		A0		INT_MSK0	E0	RW
DBB00DR1	21	W		61			A1		INT_MSK1	E1	RW
DBB00DR2	22	RW		62			A2		INT_VC	E2	RC
DBB00CR0	23	#	ARF_CR	63	RW		A3		RES_WDT	E3	W
DBB01DR0	24	#	CMP_CR0	64	#		A4		DEC_DH	E4	RC
DBB01DR1	25	W	ASY_CR	65	#		A5		DEC_DL	E5	RC
DBB01DR2	26	RW	CMP_CR1	66	RW		A6		DEC_CR0	E6	RW
DBB01CR0	27	#		67			A7		DEC_CR1	E7	RW
DCB02DR0	28	#		68		MUL1_X	A8	W	MUL0_X	E8	W
DCB02DR1	29	W		69		MUL1_Y	A9	W	MUL0_Y	E9	W
DCB02DR2	2A	RW		6A		MUL1_DH	AA	R	MUL0_DH	EA	R
DCB02CR0	2B	#		6B		MUL1_DL	AB	R	MUL0_DL	EB	R
DCB03DR0	2C	#	TMP_DR0	6C	RW	ACC1_DR1	AC	RW	ACC0_DR1	EC	RW
DCB03DR1	2D	W	TMP_DR1	6D	RW	ACC1_DR0	AD	RW	ACC0_DR0	ED	RW
DCB03DR2	2E	RW	TMP_DR2	6E	RW	ACC1_DR3	AE	RW	ACC0_DR3	EE	RW
DCB03CR0	2F	#	TMP_DR3	6F	RW	ACC1_DR2	AF	RW	ACC0_DR2	EF	RW
DBB10DR0	30	#	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBB10DR1	31	W	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBB10DR2	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
DBB10CR0	33	#	ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBB11DR0	34	#	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBB11DR1	35	W	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBB11DR2	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
DBB11CR0	37	#	ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12DR0	38	#	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	
DCB12DR1	39	W	ACB02CR0	79	RW	RDI1SYN	B9	RW		F9	
DCB12DR2	3A	RW	ACB02CR1	7A	RW	RDI1IS	BA	RW		FA	
DCB12CR0	3B	#	ACB02CR2	7B	RW	RDI1LT0	BB	RW		FB	
DCB13DR0	3C	#	ACB03CR3	7C	RW	RDI1LT1	BC	RW		FC	
DCB13DR1	3D	W	ACB03CR0	7D	RW	RDI1RO0	BD	RW		FD	
DCB13DR2	3E	RW	ACB03CR1	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
DCB13CR0	3F	#	ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed.   # Access is bit specific.

Table 6. Register Map Bank 1 Table: Configuration Space

Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access	Name	Addr (1,Hex)	Access
PRT0DM0	00	RW	DBB20FN	40	RW	ASC10CR0	80	RW	RDI2RI	C0	RW
PRT0DM1	01	RW	DBB20IN	41	RW	ASC10CR1	81	RW	RDI2SYN	C1	RW
PRT0IC0	02	RW	DBB20OU	42	RW	ASC10CR2	82	RW	RDI2IS	C2	RW
PRT0IC1	03	RW		43		ASC10CR3	83	RW	RDI2LT0	C3	RW
PRT1DM0	04	RW	DBB21FN	44	RW	ASD11CR0	84	RW	RDI2LT1	C4	RW
PRT1DM1	05	RW	DBB21IN	45	RW	ASD11CR1	85	RW	RDI2RO0	C5	RW
PRT1IC0	06	RW	DBB21OU	46	RW	ASD11CR2	86	RW	RDI2RO1	C6	RW
PRT1IC1	07	RW		47		ASD11CR3	87	RW		C7	
PRT2DM0	08	RW	DCB22FN	48	RW	ASC12CR0	88	RW	RDI3RI	C8	RW
PRT2DM1	09	RW	DCB22IN	49	RW	ASC12CR1	89	RW	RDI3SYN	C9	RW
PRT2IC0	0A	RW	DCB22OU	4A	RW	ASC12CR2	8A	RW	RDI3IS	CA	RW
PRT2IC1	0B	RW		4B		ASC12CR3	8B	RW	RDI3LT0	CB	RW
PRT3DM0	0C	RW	DCB23FN	4C	RW	ASD13CR0	8C	RW	RDI3LT1	CC	RW
PRT3DM1	0D	RW	DCB23IN	4D	RW	ASD13CR1	8D	RW	RDI3RO0	CD	RW
PRT3IC0	0E	RW	DCB23OU	4E	RW	ASD13CR2	8E	RW	RDI3RO1	CE	RW
PRT3IC1	0F	RW		4F		ASD13CR3	8F	RW		CF	
PRT4DM0	10	RW	DBB30FN	50	RW	ASD20CR0	90	RW	GDI_O_IN	D0	RW
PRT4DM1	11	RW	DBB30IN	51	RW	ASD20CR1	91	RW	GDI_E_IN	D1	RW
PRT4IC0	12	RW	DBB30OU	52	RW	ASD20CR2	92	RW	GDI_O_OU	D2	RW
PRT4IC1	13	RW		53		ASD20CR3	93	RW	GDI_E_OU	D3	RW
PRT5DM0	14	RW	DBB31FN	54	RW	ASC21CR0	94	RW		D4	
PRT5DM1	15	RW	DBB31IN	55	RW	ASC21CR1	95	RW		D5	
PRT5IC0	16	RW	DBB31OU	56	RW	ASC21CR2	96	RW		D6	
PRT5IC1	17	RW		57		ASC21CR3	97	RW		D7	
	18		DCB32FN	58	RW	ASD22CR0	98	RW		D8	
	19		DCB32IN	59	RW	ASD22CR1	99	RW		D9	
	1A		DCB32OU	5A	RW	ASD22CR2	9A	RW		DA	
	1B			5B		ASD22CR3	9B	RW		DB	
	1C		DCB33FN	5C	RW	ASC23CR0	9C	RW		DC	
	1D		DCB33IN	5D	RW	ASC23CR1	9D	RW	OSC_GO_EN	DD	RW
	1E		DCB33OU	5E	RW	ASC23CR2	9E	RW	OSC_CR4	DE	RW
	1F			5F		ASC23CR3	9F	RW	OSC_CR3	DF	RW
DBB00FN	20	RW	CLK_CR0	60	RW		A0		OSC_CR0	E0	RW
DBB00IN	21	RW	CLK_CR1	61	RW		A1		OSC_CR1	E1	RW
DBB00OU	22	RW	ABF_CR0	62	RW		A2		OSC_CR2	E2	RW
	23		AMD_CR0	63	RW		A3		VLT_CR	E3	RW
DBB01FN	24	RW		64			A4		VLT_CMP	E4	R
DBB01IN	25	RW		65			A5			E5	
DBB01OU	26	RW	AMD_CR1	66	RW		A6			E6	
	27		ALT_CR0	67	RW		A7			E7	
DCB02FN	28	RW	ALT_CR1	68	RW		A8		IMO_TR	E8	W
DCB02IN	29	RW	CLK_CR2	69	RW		A9		ILO_TR	E9	W
DCB02OU	2A	RW		6A			AA		BDG_TR	EA	RW
	2B			6B			AB		ECO_TR	EB	W
DCB03FN	2C	RW	TMP_DR0	6C	RW		AC			EC	
DCB03IN	2D	RW	TMP_DR1	6D	RW		AD			ED	
DCB03OU	2E	RW	TMP_DR2	6E	RW		AE			EE	
	2F		TMP_DR3	6F	RW		AF			EF	
DBB10FN	30	RW	ACB00CR3	70	RW	RDI0RI	B0	RW		F0	
DBB10IN	31	RW	ACB00CR0	71	RW	RDI0SYN	B1	RW		F1	
DBB10OU	32	RW	ACB00CR1	72	RW	RDI0IS	B2	RW		F2	
	33		ACB00CR2	73	RW	RDI0LT0	B3	RW		F3	
DBB11FN	34	RW	ACB01CR3	74	RW	RDI0LT1	B4	RW		F4	
DBB11IN	35	RW	ACB01CR0	75	RW	RDI0RO0	B5	RW		F5	
DBB11OU	36	RW	ACB01CR1	76	RW	RDI0RO1	B6	RW		F6	
	37		ACB01CR2	77	RW		B7		CPU_F	F7	RL
DCB12FN	38	RW	ACB02CR3	78	RW	RDI1RI	B8	RW		F8	
DCB12IN	39	RW	ACB02CR0	79	RW	RDI1SYN	B9	RW		F9	
DCB12OU	3A	RW	ACB02CR1	7A	RW	RDI1IS	BA	RW	FLS_PR1	FA	RW
	3B		ACB02CR2	7B	RW	RDI1LT0	BB	RW		FB	
DCB13FN	3C	RW	ACB03CR3	7C	RW	RDI1LT1	BC	RW		FC	
DCB13IN	3D	RW	ACB03CR0	7D	RW	RDI1RO0	BD	RW		FD	
DCB13OU	3E	RW	ACB03CR1	7E	RW	RDI1RO1	BE	RW	CPU_SCR1	FE	#
	3F		ACB03CR2	7F	RW		BF		CPU_SCR0	FF	#

Blank fields are Reserved and should not be accessed.   # Access is bit specific.

Electrical Specifications

This section presents the DC and AC electrical specifications of the automotive CY8C29x66 PSoC device. For the most up to date electrical specifications, confirm that you have the most recent data sheet by visiting http://www.cypress.com.

Specifications are valid for –40 °C $\leq T_A \leq$ 125 °C and $T_J \leq$ 135 °C, except where noted.

Figure 5. Voltage versus CPU Frequency
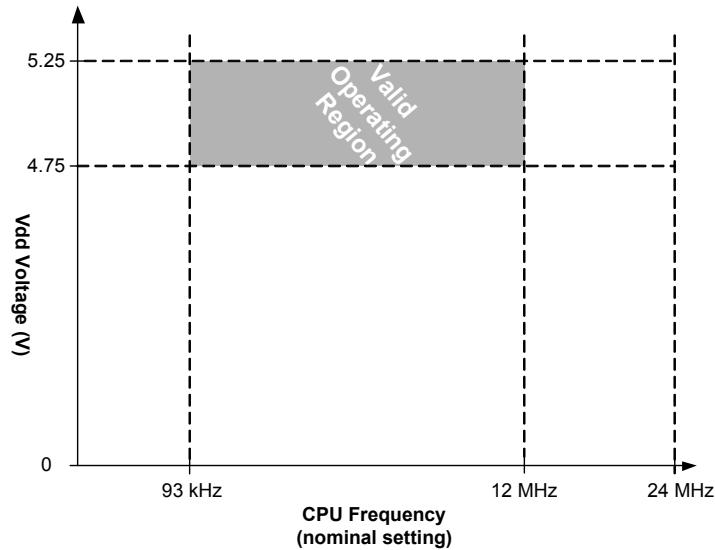
Absolute Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Table 7. Absolute Maximum Ratings

Symbol	Description	Min	Typ	Max	Units	Notes
T_{STG}	Storage Temperature	–55	+25	+125	°C	Higher storage temperatures reduce data retention time. Recommended storage temperature is +25 °C ± 25 °C. Storage temperatures above 65 °C degrade reliability. Maximum combined storage and operational time at +125 °C is 7000 hours.
$T_{BAKETEMP}$	Bake Temperature	–	125	See package label	°C	
$T_{BAKETIME}$	Bake Time	See package label	–	72	Hours	
T_A	Ambient Temperature with Power Applied	–40	–	+125	°C	
Vdd	Supply Voltage on Vdd Relative to Vss	–0.5	–	+6.0	V	
V_{IO}	DC Input Voltage	Vss – 0.5	–	Vdd + 0.5	V	
V_{IOZ}	DC Voltage Applied to Tri-state	Vss – 0.5	–	Vdd + 0.5	V	
I_{MIO}	Maximum Current into any Port Pin	–25	–	+25	mA	
ESD	Electro Static Discharge Voltage	2000	–	–	V	Human Body Model ESD.
LU	Latch up Current	–	–	200	mA	

Operating Temperature

Table 8. Operating Temperature

Symbol	Description	Min	Typ	Max	Units	Notes
T_A	Ambient Temperature	–40	–	+125	°C	
T_J	Junction Temperature	–40	–	+135	°C	The temperature rise from ambient to junction is package specific. See Thermal Impedances on page 30. The user must limit the power consumption to comply with this requirement.

DC Electrical Characteristics

DC Chip-Level Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq T_A \leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 9. DC Chip-Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
Vdd	Supply Voltage	4.75	–	5.25	V	
I_{DD}	Supply Current	–	8	15	mA	Conditions are –40 °C $\leq T_A \leq$ 125 °C, CPU=3 MHz, 48 MHz disabled. VC1 = 1.5 MHz, VC2 = 93.75 kHz, VC3 = 0.366 kHz. Analog power = off.
I_{SB}	Sleep (Mode) Current with POR, LVD, Sleep Timer, and WDT.[7]	–	6	16	μA	Conditions are with internal low speed oscillator active, –40 °C $\leq T_A \leq$ 55 °C. Analog power = off.
I_{SBH}	Sleep (Mode) Current with POR, LVD, Sleep Timer, and WDT at high temperature[7]	–	6	100	μA	Conditions are with internal low speed oscillator active, 55 °C < $T_A \leq$ 125 °C. Analog power = off.
I_{SBXTL}	Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and external crystal.[7]	–	8	18	μA	Conditions are with properly loaded, 1 μW max, 32.768 kHz crystal. –40 °C $\leq T_A \leq$ 55 °C. Analog power = off.
I_{SBXTLH}	Sleep (Mode) Current with POR, LVD, Sleep Timer, WDT, and external crystal at high temperature.[7]	–	8	100	μA	Conditions are with properly loaded, 1 μW max, 32.768 kHz crystal. 55 °C < $T_A \leq$ 125 °C. Analog power = off.
V_{REF}	Reference Voltage (Bandgap)	1.25	1.3	1.35	V	

Note
7. Standby current includes all functions (POR, LVD, WDT, Sleep Timer) needed for reliable system operation. This must be compared with devices that have similar functions enabled.

DC General Purpose I/O Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T$_A$ $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 10. DC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R$_{PU}$	Pull up Resistor	4	5.6	8	kΩ	
R$_{PD}$	Pull down Resistor	4	5.6	8	kΩ	
V$_{OH}$	High Output Level	3.5	–	–	V	I$_{OH}$ = 10 mA, Vdd = 4.75 to 5.25 V (maximum 40 mA on even port pins (for example, P0[2], P1[4]), maximum 40 mA on odd port pins (for example, P0[3], P1[5])). 80 mA maximum combined I$_{OH}$ budget.
V$_{OL}$	Low Output Level	–	–	0.75	V	I$_{OL}$ = 25 mA, Vdd = 4.75 to 5.25 V (maximum 100 mA on even port pins (for example, P0[2], P1[4]), maximum 100 mA on odd port pins (for example, P0[3], P1[5])). 150 mA maximum combined I$_{OL}$ budget.
I$_{OH}$	High Level Source Current	10	–	–	mA	V$_{OH}$ $\geq$ Vdd–1.0 V, see the limitations of the total current in the note for V$_{OH}$
I$_{OL}$	Low Level Sink Current	25	–	–	mA	V$_{OL}$ $\leq$ 0.75 V, see the limitations of the total current in the note for V$_{OL}$
V$_{IL}$	Input Low Level	–	–	0.8	V	
V$_{IH}$	Input High Level	2.1	–		V	
V$_H$	Input Hysterisis	–	60	–	mV	
I$_{IL}$	Input Leakage (Absolute Value)	–	1	–	nA	Gross tested to 1 μA.
C$_{IN}$	Capacitive Load on Pins as Input	–	3.5	10	pF	Package and pin dependent. Temp = 25 °C.
C$_{OUT}$	Capacitive Load on Pins as Output	–	3.5	10	pF	Package and pin dependent. Temp = 25 °C.

DC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T$_A$ ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

The Operational Amplifier is a component of both the Analog Continuous Time (CT) PSoC blocks and the Analog Switched Capacitors (SC) PSoC blocks. The guaranteed specifications are measured in the Analog Continuous Time (CT) PSoC blocks.

Table 11. DC Operational Amplifier Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V$_{OSOA}$	Input Offset Voltage (absolute value) Low Power Input Offset Voltage (absolute value) Mid Power Input Offset Voltage (absolute value) High Power	– – –	1.6 1.3 1.2	11 9 9	mV mV mV	
TCV$_{OSOA}$	Input Offset Voltage Drift	–	7.0	35.0	μV/°C	
I$_{EBOA}$	Input Leakage Current (Port 0 Analog Pins)	–	200	–	pA	Gross tested to 1 μA
C$_{INOA}$	Input Capacitance (Port 0 Analog Pins)	–	4.5	9.5	pF	Package and pin dependent. Temp = 25 °C.
V$_{CMOA}$	Common Mode Voltage Range Common Mode Voltage Range (high power or high opamp bias)	0.0 0.5	– –	Vdd Vdd – 0.5	V –	The common-mode input voltage range is measured through an analog output buffer. The specification includes the limitations imposed by the characteristics of the analog output buffer.
G$_{OLOA}$	Open Loop Gain	–	80	–	dB	
V$_{OHIGHOA}$	High Output Voltage Swing (worst case internal load) Power = Low Power = Medium Power = High	 Vdd – 0.2 Vdd – 0.2 Vdd – 0.5	 – – –	 – – –	 V V V	
V$_{OLOWOA}$	Low Output Voltage Swing (worst case internal load) Power = Low Power = Medium Power = High	 – – –	 – – –	 0.2 0.2 0.5	 V V V	
I$_{SOA}$	Supply Current (including associated AGND buffer) Power = Low, Opamp Bias = Low Power = Low, Opamp Bias = High Power = Medium, Opamp Bias = Low Power = Medium, Opamp Bias = High Power = High, Opamp Bias = Low Power = High, Opamp Bias = High	 – – – – – –	 150 300 600 1200 2400 4600	 200 400 800 1600 3200 6400	 μA μA μA μA μA μA	
PSRR$_{OA}$	Supply Voltage Rejection Ratio	–	80	–	dB	Vss ≤ VIN ≤ (Vdd - 2.25) or (Vdd – 1.25 V) ≤ VIN ≤ Vdd

DC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 12. DC Low Power Comparator Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{REFLPC}	Low power comparator (LPC) reference voltage range	0.2	–	Vdd – 1	V	
I_{SLPC}	LPC supply current	–	10	40	μA	
V_{OSLPC}	LPC voltage offset	–	2.5	30	mV	

DC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 13. DC Analog Output Buffer Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{OSOB}	Input Offset Voltage (Absolute Value)	–	3	18	mV	
TCV_{OSOB}	Input Offset Voltage Drift	–	+6	–	μV/°C	
V_{CMOB}	Common-Mode Input Voltage Range	0.5	–	Vdd – 1.0	V	
R_{OUTOB}	Output Resistance	–	1	–	W	
$V_{OHIGHOB}$	High Output Voltage Swing (Load = 32Ω to Vdd/2)	0.5 x Vdd + 1.1	–	–	V	
V_{OLOWOB}	Low Output Voltage Swing (Load = 32Ω to Vdd/2)	–	–	0.5 x Vdd – 1.3	V	
I_{SOB}	Supply Current Including Bias Cell (No Load) Power = Low Power = High	– –	1.1 2.6	5.1 8.8	mA mA	
$PSRR_{OB}$	Supply Voltage Rejection Ratio	–	64	–	dB	

DC Analog Reference Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

The guaranteed specifications for RefHI and RefLO are measured through the analog continuous time PSoC blocks. The power levels for RefHI and RefLO refer to the analog reference control register. AGND is measured at P2[4] in AGND bypass mode. Each analog continuous time PSoC block adds a maximum of 10 mV additional offset error to guaranteed AGND specifications from the local AGND buffer. Reference control power can be set to medium or high unless otherwise noted.

Note Avoid using P2[4] for digital signaling when using an analog resource that depends on the Analog Reference. Some coupling of the digital signal may appear on the AGND.

Table 14. DC Analog Reference Specifications

Symbol	Description	Min	Typ	Max	Units
V_{BG}	Bandgap Voltage Reference	1.25	1.30	1.35	V
–	AGND = Vdd/2[8]	Vdd/2 – 0.02	Vdd/2	Vdd/2 + 0.02	V
–	AGND = 2 x BandGap[8]	2.4	2.6	2.8	V
–	AGND = P2[4] (P2[4] = Vdd/2)[8]	P2[4] – 0.02	P2[4]	P2[4] + 0.02	V
–	AGND = BandGap[8]	1.23	1.3	1.37	V
–	AGND = 1.6 x BandGap[8]	1.98	2.08	2.14	V
–	AGND Column to Column Variation (AGND=Vdd/2)[8]	0.035	0.000	0.035	V
–	RefHi = Vdd/2 + BandGap[9]	Vdd/2 + 1.15	Vdd/2 + 1.30	Vdd/2 + 1.45	V
–	RefHi = 3 x BandGap[9]	3.65	3.9	4.15	V
–	RefHi = 2 x BandGap + P2[6] (P2[6] = 1.3 V)[9]	P2[6] + 2.4	P2[6] + 2.6	P2[6] + 2.8	V
–	RefHi = P2[4] + BandGap (P2[4] = Vdd/2)[9]	P2[4] + 1.24	P2[4] + 1.30	P2[4] + 1.36	V
–	RefHi = P2[4] + P2[6] (P2[4] = Vdd/2, P2[6] = 1.3 V)[9]	P2[4] + P2[6] – 0.1	P2[4] + P2[6]	P2[4] + P2[6] + 0.1	V
–	RefHi = 2 x BandGap[9]	2.4	2.6	2.8	V
–	RefHi = 3.2 x BandGap[9]	3.9	4.16	4.42	V
–	RefLo = Vdd/2 - BandGap[9]	Vdd/2 – 1.45	Vdd/2 – 1.3	Vdd/2 – 1.15	V
–	RefLo = BandGap[9]	1.15	1.30	1.45	V
–	RefLo = 2 x BandGap – P2[6] (P2[6] = 1.3 V)[9]	2.4 – P2[6]	2.6 – P2[6]	2.8 – P2[6]	V
–	RefLo = P2[4] - BandGap (P2[4] = Vdd/2)[9]	P2[4] – 1.45	P2[4] – 1.3	P2[4] – 1.15	V
–	RefLo = P2[4] – P2[6] (P2[4] = Vdd/2, P2[6] = 1.3 V)[9]	P2[4] – P2[6] – 0.1	P2[4] – P2[6]	P2[4] – P2[6] + 0.1	V

DC Analog PSoC Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 15. DC Analog PSoC Block Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{CT}	Resistor Unit Value (Continuous Time)	–	12.24	–	kΩ	
C_{SC}	Capacitor Unit Value (Switch Cap)	–	80	–	fF	

Notes
8. This specification is only valid when CT Block Power = High. AGND tolerance includes the offsets of the local buffer in the PSoC block.
9. This specification is only valid when Ref Control Power = High.

DC POR and LVD Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T_A $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 16. DC POR and LVD Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{PPOR2}	Vdd Value for PPOR Trip PORLEV[1:0] = 10b	–	4.55	4.70	V	Vdd must be greater than or equal to 2.5 V during startup, reset from the XRES pin, or reset from watchdog.
V_{LVD6} V_{LVD7}	Vdd Value for LVD Trip VM[2:0] = 110b VM[2:0] = 111b	4.62 4.710	4.73 4.814	4.83 4.950	V V	

DC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T_A $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 17. DC Programming Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
I_{DDP}	Supply Current During Programming or Verify	–	15	30	mA	
V_{ILP}	Input Low Voltage During Programming or Verify	–	–	0.8	V	
V_{IHP}	Input High Voltage During Programming or Verify	2.1	–	–	V	
I_{ILP}	Input Current when Applying V_{ILP} to P1[0] or P1[1] During Programming or Verify	–	–	0.2	mA	Driving internal pull down resistor.
I_{IHP}	Input Current when Applying V_{IHP} to P1[0] or P1[1] During Programming or Verify	–	–	1.5	mA	Driving internal pull down resistor.
V_{OLV}	Output Low Voltage During Programming or Verify	–	–	0.75	V	
V_{OHV}	Output High Voltage During Programming or Verify	3.5	–	Vdd	V	
$Flash_{ENPB}$	Flash Endurance (per block)[10]	100	–	–	–	Erase/write cycles per block.
$Flash_{ENT}$	Flash Endurance (total)[10, 11]	51,200	–	–	–	Erase/write cycles.
$Flash_{DR}$	Flash Data Retention[12]	15	–	–	Years	

Notes
10. For the full temperature range, the user must employ a temperature sensor user module (FlashTemp) or other temperature sensor, and feed the result to the temperature argument before writing. Refer to the Flash APIs Application Note AN2015 at http://www.cypress.com under Application Notes for more information.
11. The maximum total number of allowed erase/write cycles is the minimum $Flash_{ENPB}$ value multiplied by the number of flash blocks in the device.
12. Flash data retention based on the use condition of $\leq$ 7000 hours at T_A $\leq$ 125 °C and the remaining time at T_A $\leq$ 65 °C.

AC Electrical Characteristics

*AC Chip-Level Specifications*

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 18. AC Chip-Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{IMO24}	Internal Main Oscillator Frequency for 24 MHz	23.04[13]	24	24.96[13]	MHz	Trimmed. Utilizing factory trim values.
F_{CPU1}	CPU Frequency (5 V Vdd Nominal)	0.09[13]	12	12.48[13]	MHz	
F_{24M}	Digital PSoC Block Frequency	0	24	24.96[14, 13]	MHz	
F_{32K1}	Internal Low Speed Oscillator Frequency	15	32	64	kHz	This specification applies when the ILO has been trimmed.
F_{32KU}	Internal Low Speed Oscillator (ILO) Untrimmed Frequency	5	–	–	kHz	After a reset and before the M8C processor starts to execute, the ILO is not trimmed.
F_{32K2}	External Crystal Oscillator	–	32.768	–	kHz	Accuracy is capacitor and crystal dependent. 50% duty cycle.
F_{PLL}	PLL Frequency	–	23.986	–	MHz	Is a multiple (x732) of crystal frequency.
Jitter24M2	24 MHz Period Jitter (PLL)	–	–	800	ps	
$T_{PLLSLEW}$	PLL Lock Time	0.5	–	10	ms	Refer to Figure 6 on page 23.
$T_{PLLSLEWSLOW}$	PLL Lock Time for Low Gain Setting	0.5	–	50	ms	Refer to Figure 7 on page 23.
T_{OS}	External Crystal Oscillator Startup to 1%	–	1700	2620	ms	Refer to Figure 8 on page 23.
T_{OSACC}	External Crystal Oscillator Startup to 200 ppm	–	2800	3800	ms	
Jitter32k	32 kHz Period Jitter	–	100	–	ns	Refer to Figure 10 on page 23.
T_{XRST}	External Reset Pulse Width	10	–	–	µs	
DC24M	24 MHz Duty Cycle	40	50	60	%	
DC_{ILO}	Internal Low Speed Oscillator (ILO) Duty Cycle	20	50	80	%	
Step24M	24 MHz Trim Step Size	–	50	–	kHz	
Jitter24M1P	24 MHz Period Jitter (IMO) Peak-to-Peak	–	600	–	ps	Refer to Figure 9 on page 23.
Jitter24M1R	24 MHz Period Jitter (IMO) Root Mean Squared	–	–	600	ps	Refer to Figure 9 on page 23.
F_{MAX}	Maximum frequency of signal on row input or row output.	–	–	12.48[13]	MHz	
$SR_{POWERUP}$	Power Supply Slew Rate	–	–	250	V/ms	Vdd slew rate during power up.
$T_{POWERUP}$	Time between end of POR state and CPU code execution	–	16	100	ms	Power up from 0 V.

Notes
13. Accuracy derived from Internal Main Oscillator with appropriate trim for Vdd range.
14. See the individual user module data sheets for information on maximum frequencies for user modules.

Figure 6. PLL Lock Timing Diagram
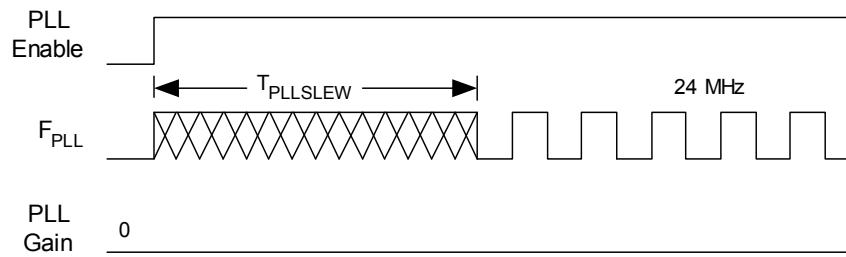
Figure 7. PLL Lock for Low Gain Setting Timing Diagram
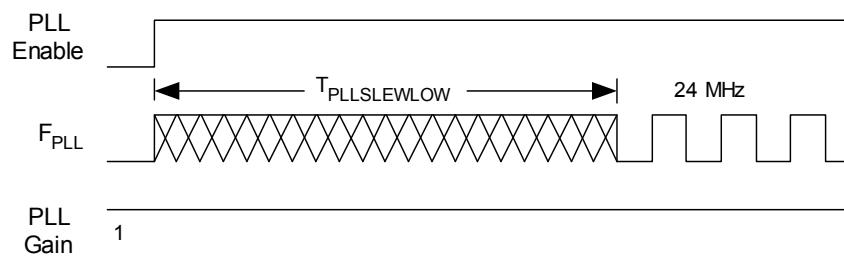
Figure 8. External Crystal Oscillator Startup Timing Diagram
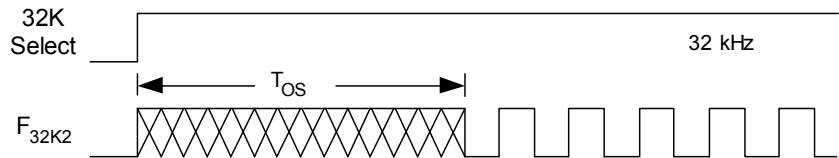
Figure 9. 24 MHz Period Jitter (IMO) Timing Diagram
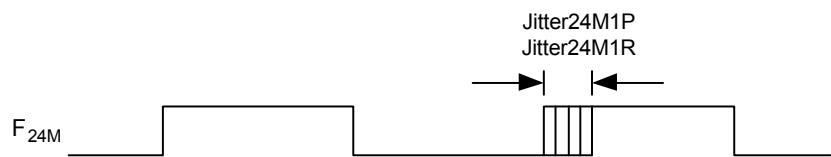
Figure 10. 32 kHz Period Jitter (ECO) Timing Diagram
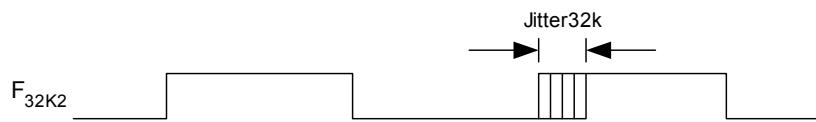
AC General Purpose I/O Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 19. AC GPIO Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{GPIO}	GPIO Operating Frequency	0	–	12.48[13]	MHz	Normal Strong Mode
TRiseF	Rise Time, Normal Strong Mode, Cload = 50 pF	2	–	22	ns	10% - 90%
TFallF	Fall Time, Normal Strong Mode, Cload = 50 pF	2	–	22	ns	10% - 90%
TRiseS	Rise Time, Slow Strong Mode, Cload = 50 pF	9	27	–	ns	10% - 90%
TFallS	Fall Time, Slow Strong Mode, Cload = 50 pF	9	22	–	ns	10% - 90%

Figure 11. GPIO Timing Diagram
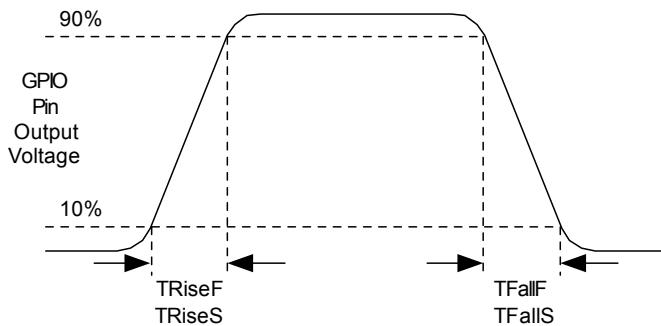
AC Operational Amplifier Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Note   Settling times, slew rates, and gain bandwidth are based on the Analog Continuous Time PSoC block.

Table 20. AC Operational Amplifier Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
SR_{ROA}	Rising Slew Rate (20% to 80%) of a 1 V Step (10 pF load, Unity Gain)					
	Power = Low, Opamp Bias = Low	0.15	–	–	V/μs	
	Power = Low, Opamp Bias = High	0.15	–	–	V/μs	
	Power = Medium, Opamp Bias = Low	0.15	–	–	V/μs	
	Power = Medium, Opamp Bias = High	1.7	–	–	V/μs	
	Power = High, Opamp Bias = Low	1.7	–	–	V/μs	
	Power = High, Opamp Bias = High	6.5	–	–	V/μs	
SR_{FOA}	Falling Slew Rate (80% to 20%) of a 1 V Step (10 pF load, Unity Gain)					
	Power = Low, Opamp Bias = Low	0.01	–	–	V/μs	
	Power = Low, Opamp Bias = High	0.01	–	–	V/μs	
	Power = Medium, Opamp Bias = Low	0.01	–	–	V/μs	
	Power = Medium, Opamp Bias = High	0.5	–	–	V/μs	
	Power = High, Opamp Bias = Low	0.5	–	–	V/μs	
	Power = High, Opamp Bias = High	4.0	–	–	V/μs	
BW_{OA}	Gain Bandwidth Product					
	Power = Low, Opamp Bias = Low	0.75	–	–	MHz	
	Power = Low, Opamp Bias = High	0.75	–	–	MHz	
	Power = Medium, Opamp Bias = Low	0.75	–	–	MHz	
	Power = Medium, Opamp Bias = High	3.1	–	–	MHz	
	Power = High, Opamp Bias = Low	3.1	–	–	MHz	
	Power = High, Opamp Bias = High	5.4	–	–	MHz	

When bypassed by a capacitor on P2[4], the noise of the analog ground signal distributed to each block is reduced by a factor of up to 5 (14 dB). This is at frequencies above the corner frequency defined by the on-chip 8.1 kΩ resistance and the external capacitor.

Figure 12. Typical AGND Noise with P2[4] Bypass
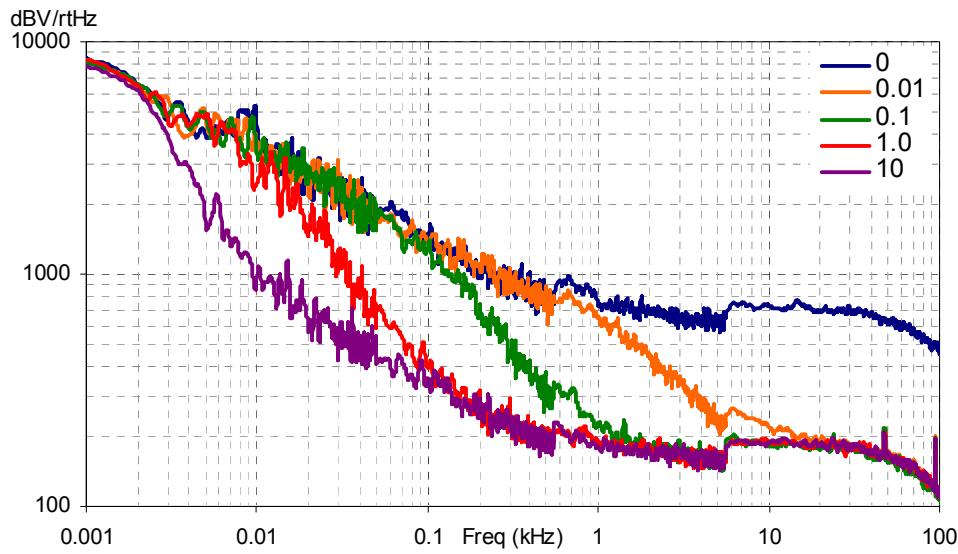
At low frequencies, the opamp noise is proportional to 1/f, power independent, and determined by device geometry. At high frequencies, increased power level reduces the noise spectrum level.

Figure 13. Typical Opamp Noise
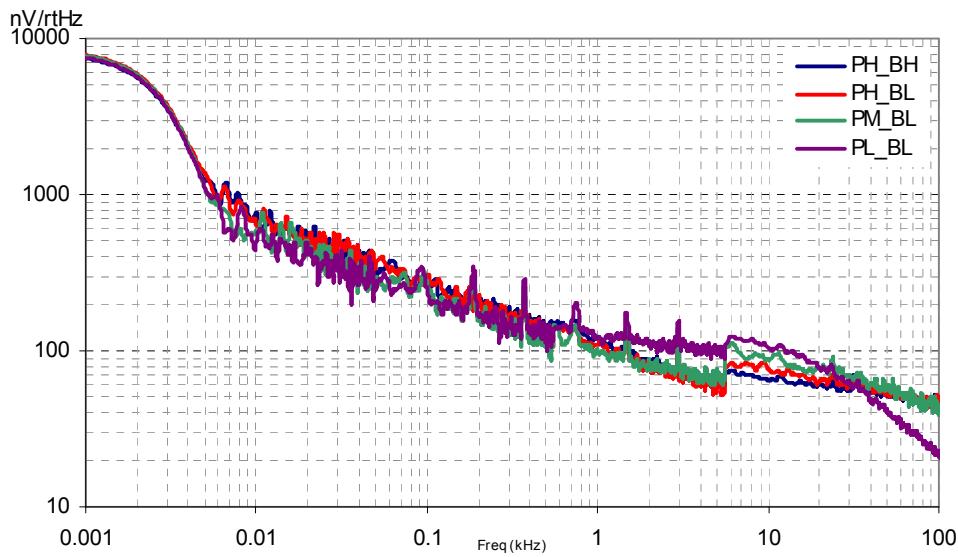
AC Low Power Comparator Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 21. AC Low Power Comparator Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
T_{RLPC}	LPC response time	–	–	50	µs	≥ 50 mV overdrive comparator reference set within V_{REFLPC}.

AC Digital Block Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 22. AC Digital Block Specifications

Function	Description	Min	Typ	Max	Units	Notes
All Functions	Maximum Block Clocking Frequency	–	–	24.96[13]	MHz	
Timer	Capture Pulse Width	50[15]	–	–	ns	
	Maximum Frequency, No Capture	–	–	24.96[13]	MHz	
	Maximum Frequency, With Capture	–	–	24.96[13]	MHz	
Counter	Enable Pulse Width	50[15]	–	–	ns	
	Maximum Frequency, No Enable Input	–	–	24.96[13]	MHz	
	Maximum Frequency, Enable Input	–	–	24.96[13]	MHz	
Dead Band	Kill Pulse Width:					
	Asynchronous Restart Mode	20	–	–	ns	
	Synchronous Restart Mode	50[15]	–	–	ns	
	Disable Mode	50[15]	–	–	ns	
	Maximum Frequency	–	–	24.96[13]	MHz	
CRCPRS (PRS Mode)	Maximum Input Clock Frequency	–	–	24.96[13]	MHz	
CRCPRS (CRC Mode)	Maximum Input Clock Frequency	–	–	24.96[13]	MHz	
SPIM	Maximum Input Clock Frequency	–	–	4.16[13]	MHz	Maximum data rate is 2.08 Mbps due to 2 × over clocking.
SPIS	Maximum Input Clock Frequency	–	–	2.08[13]	MHz	
	Width of SS_ Negated Between Transmissions	50[15]	–	–	ns	
Transmitter	Maximum Input Clock Frequency	–	–	8.32[13]	MHz	Maximum baud rate at 1.04 Mbaud due to 8 × over clocking.
Receiver	Maximum Input Clock Frequency	–	–	24.96[13]	MHz	Maximum baud rate at 3.12 Mbaud due to 8 × over clocking.

Note
15. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

AC Analog Output Buffer Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T$_A$ $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 23. AC Analog Output Buffer Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
T$_{ROB}$	Rising Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	 – –	 – –	 3 3	 μs μs	
T$_{SOB}$	Falling Settling Time to 0.1%, 1 V Step, 100pF Load Power = Low Power = High	 – –	 – –	 3 3	 μs μs	
SR$_{ROB}$	Rising Slew Rate (20% to 80%), 1 V Step, 100 pF Load Power = Low Power = High	 0.6 0.6	 – –	 – –	 V/μs V/μs	
SR$_{FOB}$	Falling Slew Rate (80% to 20%), 1 V Step, 100 pF Load Power = Low Power = High	 0.6 0.6	 – –	 – –	 V/μs V/μs	
BW$_{OB}$	Small Signal Bandwidth, 20mV$_{pp}$, 3dB BW, 100 pF Load Power = Low Power = High	 0.8 0.8	 – –	 – –	 MHz MHz	
BW$_{OB}$	Large Signal Bandwidth, 1 V$_{pp}$, 3dB BW, 100 pF Load Power = Low Power = High	 300 300	 – –	 – –	 kHz kHz	

AC External Clock Specifications

The following tables list guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T$_A$ $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 24. AC External Clock Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F$_{OSCEXT}$	Frequency	0.093	–	24.24	MHz	
–	High Period	20.6	–	–	ns	
–	Low Period	20.6	–	–	ns	
–	Power Up IMO to Switch	150	–	–	μs	

AC Programming Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C $\leq$ T$_A$ $\leq$ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 25. AC Programming Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
T$_{RSCLK}$	Rise Time of SCLK	1	–	20	ns	
T$_{FSCLK}$	Fall Time of SCLK	1	–	20	ns	
T$_{SSCLK}$	Data Set up Time to Falling Edge of SCLK	40	–	–	ns	
T$_{HSCLK}$	Data Hold Time from Falling Edge of SCLK	40	–	–	ns	
F$_{SCLK}$	Frequency of SCLK	0	–	8	MHz	
T$_{ERASEB}$	Flash Erase Time (Block)	–	10	40[10]	ms	
T$_{WRITE}$	Flash Block Write Time	–	40	160[10]	ms	
T$_{DSCLK}$	Data Out Delay from Falling Edge of SCLK	–	–	50	ns	
T$_{PRGH}$	Total Flash Block Program Time (T$_{ERASEB}$ + T$_{WRITE}$), Hot	–	–	100[10]	ms	T$_J$ $\geq$ 0 °C
T$_{PRGC}$	Total Flash Block Program Time (T$_{ERASEB}$ + T$_{WRITE}$), Cold	–	–	200[10]	ms	T$_J$ < 0 °C

AC I²C Specifications

The following table lists guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T$_A$ ≤ 125 °C. Typical parameters apply to 5 V at 25 °C and are for design guidance only.

Table 26. AC Characteristics of the I²C SDA and SCL Pins

Symbol	Description	Standard Mode		Fast Mode		Units	Notes
		Min	Max	Min	Max		
F$_{SCLI2C}$	SCL Clock Frequency	0	100[16]	0	400[16]	kHz	
T$_{HDSTAI2C}$	Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	4.0	–	0.6	–	μs	
T$_{LOWI2C}$	LOW Period of the SCL Clock	4.7	–	1.3	–	μs	
T$_{HIGHI2C}$	HIGH Period of the SCL Clock	4.0	–	0.6	–	μs	
T$_{SUSTAI2C}$	Set Up Time for a Repeated START Condition	4.7	–	0.6	–	μs	
T$_{HDDATI2C}$	Data Hold Time	0	–	0	–	μs	
T$_{SUDATI2C}$	Data Set Up Time	250	–	100[17]	–	ns	
T$_{SUSTOI2C}$	Set-up Time for STOP Condition	4.0	–	0.6	–	μs	
T$_{BUFI2C}$	Bus Free Time Between a STOP and START Condition	4.7	–	1.3	–	μs	
T$_{SPI2C}$	Pulse Width of spikes are suppressed by the input filter.	–	–	0	50	ns	

Figure 14. Definition for Timing for Fast/Standard Mode on the I²C Bus
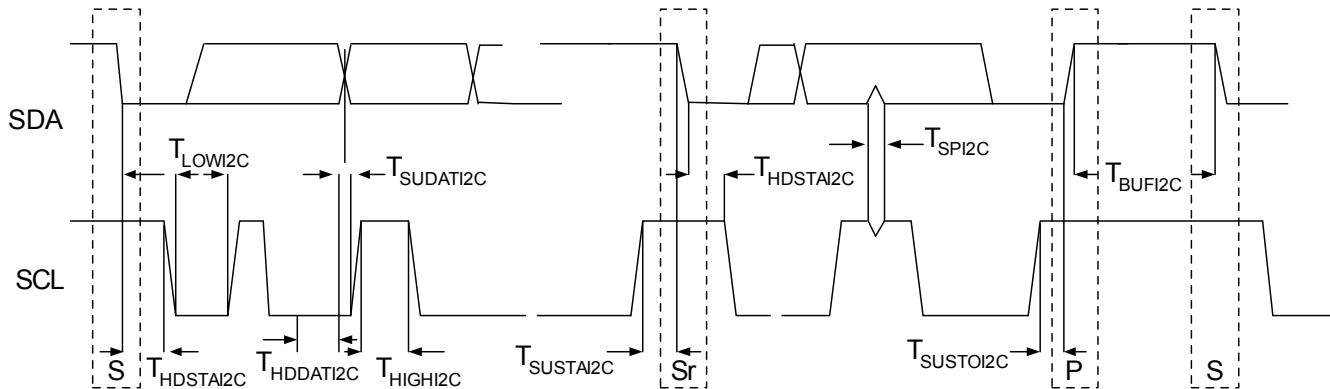
Notes
16. F$_{SCLI2C}$ is derived from SysClk of the PSoC. This specification assumes that SysClk is operating at 24 MHz, nominal. If SysClk is at a lower frequency, then the F$_{SCLI2C}$ specification adjusts accordingly.
17. A Fast-Mode I²C-bus device can be used in a Standard-Mode I²C-bus system, but the requirement T$_{SUDATI2C}$ ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t$_{rmax}$ + T$_{SUDATI2C}$ = 1000 + 250 = 1250 ns (according to the Standard-Mode I²C-bus specification) before the SCL line is released.

Packaging Information

This section illustrates the packaging specifications for the automotive CY8C29x66 PSoC device, along with the thermal impedances and solder reflow for each package and the typical package capacitance on crystal pins.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at http://www.cypress.com.

Figure 15. 28-pin SSOP (210 Mils)

51-85079 *F
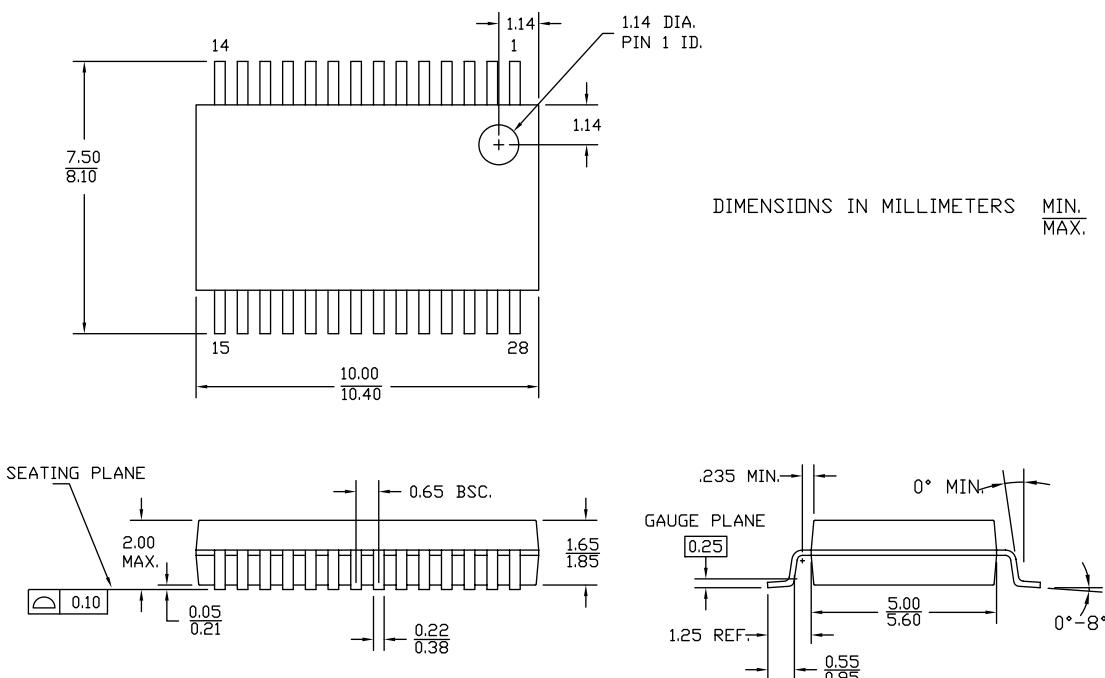
Figure 16. 48-pin SSOP (300 Mils)

51-85061 *F
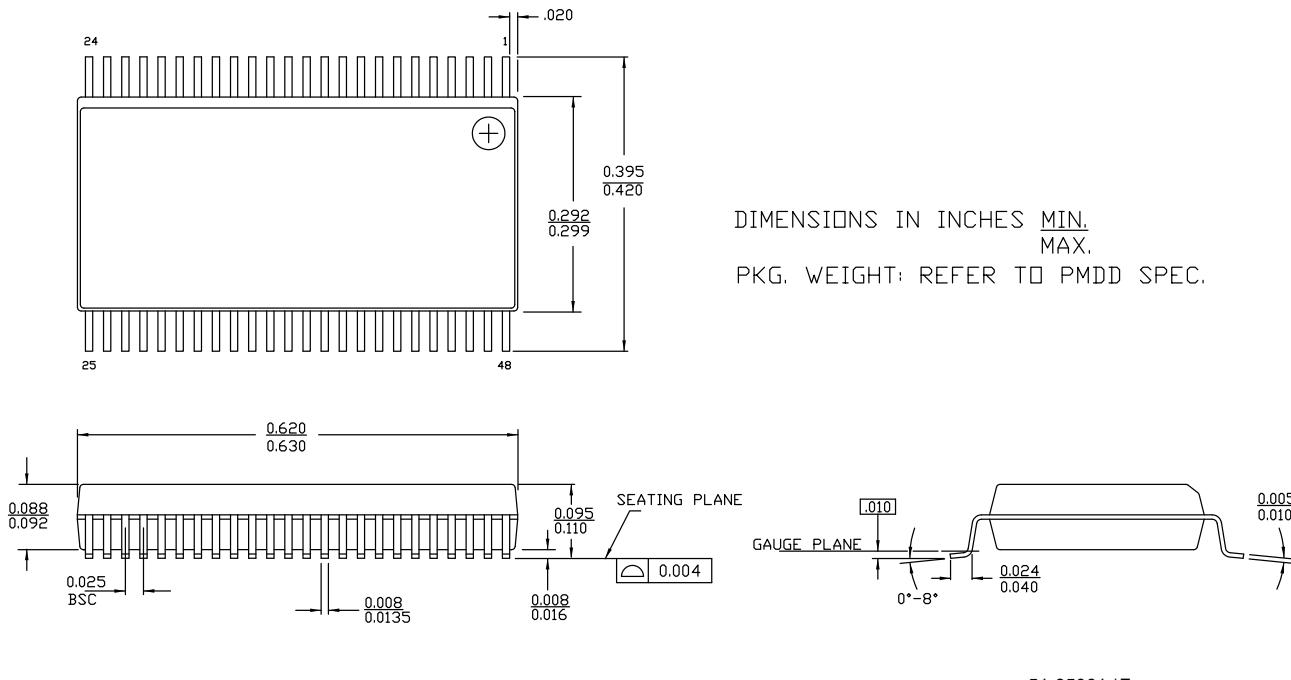
Thermal Impedances

Table 27. Thermal Impedances per Package

Package	Typical θ_{JA} [18]
28-pin SSOP	94 °C/W
48-pin SSOP	69 °C/W

Capacitance on Crystal Pins

Table 28. Typical Package Capacitance on Crystal Pins

Package	Package Capacitance
28-pin SSOP	2.8 pF
48-pin SSOP	3.3 pF

Solder Reflow Specifications

Table 29 shows the solder reflow temperature limits that must not be exceeded.

Table 29. Solder Reflow Specifications

Package	Maximum Peak Temperature (T_C)	Maximum Time above T_C − 5 °C
28-pin SSOP	260 °C	30 seconds
48-pin SSOP	260 °C	30 seconds

Note
18. $T_J = T_A + Power \times \theta_{JA}$.

Development Tool Selection

This section presents the development tools available for the CY8C29x66 family.

Software

PSoC Designer

At the core of the PSoC development software suite is PSoC Designer. Utilized by thousands of PSoC developers, this robust software has been facilitating PSoC designs for years. PSoC Designer is available free of charge at http://www.cypress.com. PSoC Designer comes with a free C compiler.

PSoC Programmer

Flexible enough to be used on the bench in development, yet suitable for factory programming, PSoC Programmer works either as a standalone programming application or it can operate directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE-Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at http://www.cypress.com.

Development Kits

All development kits can be purchased from the Cypress Online Store. The online store also has the most up to date information on kit contents, descriptions, and availability.

CY3215-DK Basic Development Kit

The CY3215-DK is for prototyping and development with PSoC Designer. This kit supports in-circuit emulation and the software interface allows users to run, halt, and single step the processor and view the contents of specific memory locations. Advanced emulation features are also supported through PSoC Designer. The kit includes:

■ ICE-Cube Unit

■ 28-pin PDIP Emulation Pod for CY8C29466-24PXI

■ 28-pin CY8C29466-24PXI PDIP PSoC Device Samples (two)

■ PSoC Designer Software CD

■ ISSP Cable

■ MiniEval Socket Programming and Evaluation board

■ Backward Compatibility Cable (for connecting to legacy Pods)

■ Universal 110/220 Power Supply (12 V)

■ European Plug Adapter

■ USB 2.0 Cable

■ Getting Started Guide

■ Development Kit Registration form

Evaluation Tools

All evaluation tools can be purchased from the Cypress Online Store. The online store also has the most up to date information on kit contents, descriptions, and availability.

CY3210-PSoCEval1

The CY3210-PSoCEval1 kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, an RS-232 port, and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

■ Evaluation Board with LCD Module

■ MiniProg Programming Unit

■ 28-pin CY8C29466-24PXI PDIP PSoC Device Sample (2)

■ PSoC Designer Software CD

■ Getting Started Guide

■ USB 2.0 Cable

CY3210-29X66 Evaluation Pod (EvalPod)

PSoC EvalPods are pods that connect to the ICE In-Circuit Emulator (CY3215-DK kit) to allow debugging capability. They can also function as a standalone device without debugging capability. The EvalPod has a 28-pin DIP footprint on the bottom for easy connection to development kits or other hardware. The top of the EvalPod has prototyping headers for easy connection to the device's pins. CY3210-29X66 provides evaluation of the CY8C29x66 PSoC device family.

Device Programmers

All device programmers can be purchased from the Cypress Online Store.

CY3210-MiniProg1

The CY3210-MiniProg1 kit allows a user to program PSoC devices via the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC via a provided USB 2.0 cable. The kit includes:

■ MiniProg Programming Unit

■ MiniEval Socket Programming and Evaluation Board

■ 28-pin CY8C29466-24PXI PDIP PSoC Device Sample

■ PSoC Designer Software CD

■ Getting Started Guide

■ USB 2.0 Cable

CY3207ISSP In-System Serial Programmer (ISSP)

The CY3207ISSP is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production-programming environment.

Note: CY3207ISSP needs special software and is not compatible with PSoC Programmer. This software is free and can be downloaded from http://www.cypress.com. The kit includes:

- CY3207 Programmer Unit
- PSoC ISSP Software CD
- 110 ~ 240 V Power Supply, Euro-Plug Adapter
- USB 2.0 Cable

Accessories (Emulation and Programming)

Table 30. Emulation and Programming Accessories

Part Number	Pin Package	Pod Kit[19]	Foot Kit[20]	Adapter[21]
CY8C29466-12PVXE	28-pin SSOP	CY3250-29X66	CY3250-28SSOP-FK	Adapters can be found at http://www.emulation.com.
CY8C29666-12PVXE	48-pin SSOP	CY3250-29X66	CY3250-48SSOP-FK	

Ordering Information

The following table lists the automotive CY8C29x66 PSoC device's key package features and ordering codes.

Table 31. CY8C29x66 Automotive PSoC Key Features and Ordering Information

Package	Ordering Code	Flash (Bytes)	RAM (Bytes)	Temperature Range	Digital PSoC Blocks	Analog PSoC Blocks	Digital I/O Pins	Analog Inputs	Analog Outputs	XRES Pin
28-pin (210 Mil) SSOP	CY8C29466-12PVXE	32 K	2 K	–40 °C to +125 °C	16	12	24	12[1]	4	Yes
28-pin (210 Mil) SSOP (Tape and Reel)	CY8C29466-12PVXET	32 K	2 K	–40 °C to +125 °C	16	12	24	12[1]	4	Yes
48-pin (300-Mil) SSOP	CY8C29666-12PVXE	32 K	2 K	–40 °C to +125 °C	16	12	44	12[1]	4	Yes

Ordering Code Definitions

CY 8 C 29 xxx-SPxx
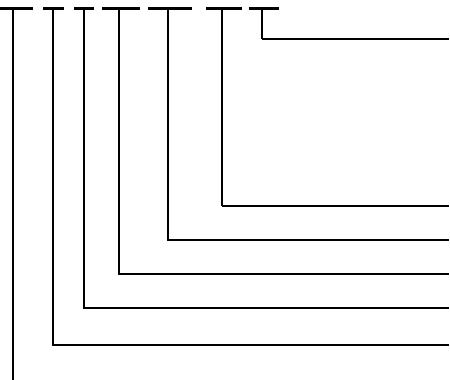
Package Type:
 PX = PDIP Pb-free
 SX = SOIC Pb-free
 PVX = SSOP Pb-free
 LFX/LTX = QFN Pb-free
 AX = TQFP Pb-free

CPU Speed: 12 MHz

Part Number

Family Code

Technology Code: C = CMOS

Marketing Code: 8 = PSoC

Company ID: CY = Cypress

Thermal Rating:
A = Automotive –40 °C to +85 °C
C = Commercial
E = Automotive Extended –40 °C to +125 °C
I = Industrial

Notes
19. Pod kit contains an emulation pod, a flex-cable (connects the pod to the ICE), two feet, and device samples.
20. Foot kit includes surface mount feet that can be soldered to the target PCB.
21. Programming adapter converts non-DIP package to DIP footprint. Specific details and ordering information for each of the adapters can be found at http://www.emulation.com.

Reference Information

Acronyms Used

The following table lists the acronyms that are used in this document.

Table 32. Acronyms

Acronym	Description	Acronym	Description
AC	alternating current	IMO	internal main oscillator
ADC	analog-to-digital converter	I/O	input/output
API	application programming interface	IPOR	imprecise power on reset
CPU	central processing unit	LSb	least-significant bit
CT	continuous time	LVD	low voltage detect
DAC	digital-to-analog converter	MSb	most-significant bit
DC	direct current	PC	program counter
ECO	external crystal oscillator	PLL	phase-locked loop
EEPROM	electrically erasable programmable read-only memory	POR	power on reset
FSR	full scale range	PPOR	precision power on reset
GPIO	general purpose IO	PSoC	Programmable System-on-Chip
GUI	graphical user interface	PWM	pulse width modulator
HBM	human body model	SC	switched capacitor
ICE	in-circuit emulator	SRAM	static random access memory
ILO	internal low speed oscillator		

Units of Measure

The following table lists the units of measure that are used in this section.

Table 33. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	μVrms	microvolts root-mean-square
dB	decibels	μW	microwatt
fF	femto farad	mA	milliampere
Hz	hertz	ms	millisecond
KB	1024 bytes	mV	millivolt
Kbit	1024 bits	nA	nanoampere
kHz	kilohertz	ns	nanosecond
kΩ	kilohm	nV	nanovolt
Mbaud	megabaud	Ω	ohm
Mbps	megabits per second	pA	picoampere
MHz	megahertz	pF	picofarad
MΩ	megaohm	pp	peak-to-peak
μA	microampere	ppm	parts per million
μF	microfarad	ps	picosecond
μH	microhenry	sps	samples per second
μs	microsecond	σ	sigma: one standard deviation
μV	microvolt	V	volt

Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or '0x' are decimal.

Document History Page

Document Title: CY8C29466, CY8C29666, Automotive – Extended Temperature PSoC® Programmable System-on-Chip Document Number: 38-12026				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	228771	06/01/2004	SFV	First release of the CY8C29x66 automotive PSoC device data sheet.
*A	271452	See ECN	HMT	Update per SFV memo. Input changes from MWR, including removing SMP.
*B	288029	See ECN	HMT	Add Reflow Peak Temp. table. Update PSoC Characteristics table. Update characterization data.
*C	473829	See ECN	HMT	Update PSoC Characteristics table. Update characterization data. Update Storage Temperature for extended temperature devices. Fix error in Register Bank 0/1. Update CY color, logo and copyright.
*D	602219	See ECN	HMT	Add Low Power Comparator (LPC) AC/DC electrical spec. tables. Add CY8C20x34 to PSoC Device Characteristics table. Update Technical Training Modules paragraph. Add ISSP note to pinout tables.
*E	2101387	See ECN	AESA	Post to www.cypress.com
*F	2545030	07/29/08	YARA	Added note to DC Analog Reference Specification table and Ordering Information
*G	2663861	02/24/09	PRKA / AESA	Updated template Removed CY8C29666-12PVXE and CY8C29666-12PVXET and related package information Updated PSoC Designer and Getting Started sections
*H	2756235	08/26/09	BTK/AESA	Changed title. Updated Features section. Updated text of PSoC Functional Overview section. Updated Getting Started section. Made corrections and minor text edits to Pinouts section. Changed the name of some sections for added clarity. Improved formatting of the register tables. Added clarifying comments to some electrical specifications. Changed T_{RAMP} specification per MASJ input. Fixed all AC specifications to conform to a ±4% IMO accuracy. Made other miscellaneous minor text edits. Deleted some non-applicable or redundant information. Added a footnote to clarify that 8 of the 12 analog inputs are regular and the other 4 are direct SC block connections. Added Development Tool Selection section. Improved the bookmark structure. Changed the T_{ROB}, T_{SOB}, V_{IHP}, $V_{OHIGHOB}$, V_{OSOB}, V_{OSOA}, C_{INOA}, $V_{OHIGHOA}$, V_{OLOWOA}, I_{SOA}, Jitter24M1P, TRiseF, and DC POR and LVD specifications according to MASJ directives.
*I	2822792	12/07/2009	BTK/AESA	Added T_{PRGH}, T_{PRGC}, I_{OL}, I_{OH}, F_{32KU}, DC_{ILO}, and $T_{POWERUP}$ electrical specifications. Updated the text of footnote 10. Added maximum values and updated typical values for T_{ERASEB} and T_{WRITE} electrical specifications. Replaced T_{RAMP} electrical specification with $SR_{POWERUP}$ electrical specification. Added "Contents" on page 2. This revision fixes CDT 63984.
*J	2888007	03/30/2010	NJF	Updated Cypress website links. Added $T_{BAKETEMP}$ and $T_{BAKETIME}$ parameters in Absolute Maximum Ratings Updated Packaging Information. Updated Development Kits and Evaluation Tools. Removed Third Party Tools and Build a PSoC Emulator into your Board. Updated Ordering Code Definitions. Updated links in Sales, Solutions, and Legal Information.
*K	3440253	11/16/2011	MYKT_UKR	Added part number CY8C29666-12PVXE to the Ordering Information table. Added 48-pin part information to Pinouts, Thermal Impedances, and Capacitance on Crystal Pins sections. Updated Accessories (Emulation and Programming) section. Updated Solder Reflow Specifications section. Included 48-Pin (300-Mil) SSOP spec to Packaging Information section.
*L	3537225	02/28/2011	VIVG	No technical updates.

Document Title: CY8C29466, CY8C29666, Automotive – Extended Temperature PSoC® Programmable System-on-Chip **Document Number: 38-12026**				
*M	3726340	08/28/2012	tess_ukr/ LURE	Updated the following sections: Getting Started, Development Tools, and Designing with PSoC Designer as all the System level designs have been de-emphasized. Changed the PWM description string from "8- to 32-bit" to "8- and 16-bit".
*N	4689330	03/16/2015	KUK	Updated Electrical Specifications: Updated DC Electrical Characteristics: Updated DC Analog Reference Specifications: Updated description. Updated Packaging Information: spec 51-85079 – Changed revision from *E to *F. spec 51-85061 – Changed revision from *E to *F. Updated to new template. Completing Sunset Review.
*O	5981600	12/01/2017	AESATMP8	Updated logo and Copyright.

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